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**(54) POLISHING PAD**

(57) Abstract:

**PROBLEM TO BE SOLVED:** To obtain a polishing pad which has satisfactory hardness and wet strength and by which clogging is eliminated by specifying the hardness of the polishing pad surface formed by a non-woven fabric impregnated with high molecular elastic polymer.

**SOLUTION:** A non-woven fabric for forming a polishing pad is not especially limited if it is formed by a fiber. To heighten the flatness required by a polishing pad for CMP, the hardness of the obtained polishing pad surface (JIS K6301 A type) is set from 85° to 99° both inclusive, preferably from 88° to 98° both inclusive. The apparent density of the non-woven fabric is preferably from 0.2 to 0.5 both inclusive. If the apparent density of the non-woven fabric is smaller than 0.2, the hardness of the obtained non-woven fabric becomes low. If it is larger than 0.5, the obtained non-woven fabric is of so close texture that

*non-woven fabric*

the liquid permeability is deteriorated and retention and liquid discharge of slurry is deteriorated. The obtained non-woven fabric is impregnated with high molecular elastic polymer.

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